

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: R. IKEZAWA, et al.
Application No.: 10/552,441
Filed: OCTOBER 7, 2005
For: ENCAPSULATING EPOXY RESIN MOLDING MATERIAL, AND
SEMICONDUCTOR DEVICE
Group AU: 2815
Examiner: Scott E. Bauman
Confirm. No.: 7255

AMENDMENT

Mail Stop: Amendment

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

August 27, 2007

Sir:

In response to the Office Action mailed April 25, 2007, please amend the above-identified application as listed in the following, and as set forth on the following pages:

Amendments to the Claims; and

Remarks are included following the amendments.